

AMENDMENTS TO THE SPECIFICATION:

Please amend the specification at page 1, line 5 as follows:

~~Description~~ BACKGROUND OF THE INVENTION

1. Field of the Invention

Please add the following heading to the specification at page 1, line 11:

2. Description of Related Art

Please add the following heading to the specification at page 1, line 30:

BRIEF SUMMARY OF THE INVENTION

Please add the following heading to the specification at page 5, line 29:

BRIEF DESCRIPTION OF THE SEVERAL VIEWS OF THE DRAWINGS

Please add the following heading to the specification at page 6, line 22:

DETAILED DESCRIPTION OF THE INVENTION

Please amend the Abstract of the Disclosure as follows:

A process to ~~To~~ encapsulate electronic modules in a manner which is substantially resistant to water diffusion yet is carried out at moderate temperatures below 300°C, preferably below 150°C is provided. ~~The process forms , the invention provides a process for forming~~ a housing for electronic modules, in particular sensors, integrated circuits and optoelectronic components. The process includes ~~, comprising~~ the steps of: providing a substrate (1), of which at least a first substrate side (1a) is to be encapsulated[[,]]; providing a vapor-deposition glass source (20), ; arranging the first substrate side (1a) in such a manner with respect to the vapor-deposition glass source that the first substrate side (1a) can be vapor-coated; and vapor-coating the first substrate side with a glass layer (4).